

Product Change Notification - GBNG-10IBJX960

Date:

11 Jun 2019

Product Category:

8-bit Microcontrollers; 16-Bit - Microcontrollers and Digital Signal Controllers; 32-bit Microcontrollers

Affected CPNs:

Notification subject:

CCB 3300.002 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18 um and 0.25 um TSMC wafer technologies available in 100L TQFP (12x12x1mm) package at MTAI assembly site.

Notification text:
PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18 um and 0.25 um TSMC wafer technologies available in 100L TQFP (12x12x1mm) package at MTAI assembly site.

Pre Change:

Using palladium coated copper (PdCu) bond wire.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand HQ (MTAI)	Microchip Technology Thailand HQ (MTAI)
Wire material	PdCu	CuPdAu
Die attach material	3280	3280
Molding compound material	G700HA	G700HA
Lead frame material	C7025	C7025

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at MTAI assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

July 11, 2019 (date code: 1928)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	June 2019					July 2019				
Workweek	22	23	24	25	26	27	28	29	30	31



Final PCN Issue Date			X							
Qual Report Availability			X							
Estimated Implementation Date							X			

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

June 11, 2019: Issued final notification. Attached is the qualification report. Estimated first ship date(EFSD) is on July 11 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_GBNG-10IBJX960_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PIC24FJ128GB210-I/PT
PIC24FJ192GA110-E/PT
PIC24FJ192GA110-I/PT
PIC24FJ192GB110-I/PT
PIC24FJ256DA110-I/PT
PIC24FJ256DA110T-I/PT
PIC24FJ256DA210-I/PT
PIC24FJ256DA210T-I/PT
PIC24FJ256GA110-E/PT
PIC24FJ256GA110-I/PT
PIC24FJ256GA110T-I/PT
PIC24FJ256GA110T-I/PT024
PIC24FJ256GA110T-I/PT025
PIC24FJ256GA110T-I/PTC33
PIC24FJ256GB110-I/PT
PIC24FJ256GB110T-I/PT
PIC24FJ256GB110T-I/PT025
PIC24FJ256GB210-I/PT
PIC24FJ256GB210T-I/PT
PIC24FJ64GA010-I/PT
PIC24FJ64GA010-I/PTC04
PIC24FJ64GB110-I/PT
PIC24FJ96GA010-I/PT
PIC24FJ96GA010T-I/PT
PIC24HJ128GP210A-E/PT
PIC24HJ128GP210A-I/PT
PIC24HJ128GP210AT-E/PT
PIC24HJ128GP210AT-I/PT
PIC24HJ128GP210-I/PT
PIC24HJ128GP310A-E/PT
PIC24HJ128GP310A-I/PT
PIC24HJ128GP310AT-E/PT
PIC24HJ128GP310AT-I/PT
PIC24HJ128GP310-I/PT
PIC24HJ128GP510A-E/PT
PIC24HJ128GP510A-H/PT
PIC24HJ128GP510A-I/PT
PIC24HJ128GP510A-I/PT042
PIC24HJ128GP510AT-E/PT
PIC24HJ128GP510AT-H/PT
PIC24HJ128GP510AT-I/PT
PIC24HJ128GP510AT-I/PT042
PIC24HJ128GP510-I/PT
PIC24HJ256GP210A-E/PT
PIC24HJ256GP210A-I/PT
PIC24HJ256GP210-I/PT

GBNG-10IBJX960 - CCB 3300.002 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18 um and 0.25 um TSMC wafer technologies available in 100L TQFP (12x12x1mm) package at MTAI assembly site.

PIC24HJ256GP210I-I/PT
PIC24HJ256GP610A-E/PT
PIC24HJ256GP610A-H/PT
PIC24HJ256GP610A-I/PT
PIC24HJ256GP610AT-I/PT
PIC24HJ256GP610-I/PT
PIC24HJ256GP610T-I/PT
PIC24HJ64GP210A-E/PT
PIC24HJ64GP210A-I/PT
PIC24HJ64GP210AT-E/PT
PIC24HJ64GP210AT-I/PT
PIC24HJ64GP210-I/PT
PIC24HJ64GP510A-E/PT
PIC24HJ64GP510A-I/PT
PIC24HJ64GP510AT-E/PT
PIC24HJ64GP510AT-I/PT
PIC24HJ64GP510-I/PT
PIC24HJ64GP510T-I/PT
PIC32MX320F128L-80I/PT
PIC32MX320F128L-80V/PT
PIC32MX320F128LT-80I/PT
PIC32MX320F128LT-80V/PT
PIC32MX340F128L-80I/PT
PIC32MX340F128L-80V/PT
PIC32MX340F128LT-80I/PT
PIC32MX340F128LT-80V/PT
PIC32MX360F256L-80I/PT
PIC32MX360F256L-80I/PT023
PIC32MX360F256L-80V/PT
PIC32MX360F256LT-80I/PT
PIC32MX360F256LT-80V/PT
PIC32MX360F512L-80I/PT
PIC32MX360F512L-80V/PT
PIC32MX360F512LT-80I/PT
PIC32MX360F512LT-80V/PT
PIC32MX440F128L-80I/PT
PIC32MX440F128L-80V/PT
PIC32MX440F128LT-80I/PT
PIC32MX440F128LT-80V/PT
PIC32MX460F256L-80I/PT
PIC32MX460F256L-80V/PT
PIC32MX460F256LT-80I/PT
PIC32MX460F256LT-80V/PT
PIC32MX460F512L-80I/PT
PIC32MX460F512L-80I/PTB21
PIC32MX460F512L-80V/PT
PIC32MX460F512LT-80I/PT
PIC32MX460F512LT-80I/PT024
PIC32MX460F512LT-80I/PT025

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PIC32MX460F512LT-80I/PT026

PIC32MX460F512LT-80I/PTB21

PIC32MX460F512LT-80V/PT

PIC32MX534F064L-I/PT

PIC32MX534F064LT-I/PT

PIC32MX534F064LT-V/PT

PIC32MX534F064L-V/PT

PIC32MX564F064L-I/PT

PIC32MX564F064LT-I/PT

PIC32MX564F064LT-V/PT

PIC32MX564F064L-V/PT

PIC32MX564F128L-I/PT

PIC32MX564F128LT-I/PT

PIC32MX564F128LT-V/PT

PIC32MX564F128L-V/PT

PIC32MX575F256L-80I/PT

PIC32MX575F256L-80V/PT

PIC32MX575F256LT-80I/PT

PIC32MX575F256LT-80V/PT

PIC32MX575F512L-80I/PT

PIC32MX575F512L-80I/PT024

PIC32MX575F512L-80I/PT025

PIC32MX575F512L-80I/PTC21

PIC32MX575F512L-80V/PT

PIC32MX575F512L-80V/PTC22

PIC32MX575F512LT-80I/PT

PIC32MX575F512LT-80I/PT024

PIC32MX575F512LT-80I/PT025

PIC32MX575F512LT-80V/PT

PIC32MX575F512LT-80V/PTC22

PIC32MX664F064L-I/PT

PIC32MX664F064LT-I/PT

PIC32MX664F064LT-V/PT

PIC32MX664F064L-V/PT

PIC32MX664F128L-I/PT

PIC32MX664F128LT-I/PT

PIC32MX664F128LT-V/PT

PIC32MX664F128L-V/PT

PIC32MX675F256L-80I/PT

PIC32MX675F256L-80V/PT

PIC32MX675F256LT-80I/PT

PIC32MX675F256LT-80V/PT

PIC32MX675F512L-80I/PT

PIC32MX675F512L-80V/PT

PIC32MX675F512LT-80I/PT

PIC32MX675F512LT-80V/PT

PIC32MX695F512L-80I/PT

PIC32MX695F512L-80I/PT020

PIC32MX695F512L-80I/PT021

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PIC32MX695F512L-80I/PT023

PIC32MX695F512L-80I/PTD21

PIC32MX695F512L-80I/PTD22

PIC32MX695F512L-80V/PT

PIC32MX695F512LT-80I/PT

PIC32MX695F512LT-80I/PTD21

PIC32MX695F512LT-80I/PTD22

PIC32MX695F512LT-80V/PT

PIC32MX764F128L-I/PT

PIC32MX764F128LT-I/PT

PIC32MX764F128LT-V/PT

PIC32MX764F128L-V/PT

PIC32MX775F256L-80I/PT

PIC32MX775F256L-80V/PT

PIC32MX775F256LT-80I/PT

DSPIC33EP256MU810-E/PT

DSPIC33EP256MU810-I/PT

DSPIC33EP256MU810T-E/PT

DSPIC33EP256MU810T-I/PT

DSPIC33EP256MU810T-I/PTC02

DSPIC33EP512MU810-E/PT

DSPIC33EP512MU810-E/PTC03

DSPIC33EP512MU810-I/PT

DSPIC33EP512MU810T-E/PT

DSPIC33EP512MU810T-I/PT

DSPIC33FJ128GP310A-E/PT

DSPIC33FJ128GP310A-I/PT

DSPIC33FJ128GP310AT-E/PT

DSPIC33FJ128GP310AT-I/PT

DSPIC33FJ128GP310-I/PT

DSPIC33FJ128GP710A-E/PT

DSPIC33FJ128GP710A-H/PT

DSPIC33FJ128GP710A-I/PT

DSPIC33FJ128GP710AT-E/PT

DSPIC33FJ128GP710AT-H/PT

DSPIC33FJ128GP710AT-I/PT

DSPIC33FJ128GP710AT-I/PTB21

DSPIC33FJ128GP710-I/PT

DSPIC33FJ128MC510A-E/PT

DSPIC33FJ128MC510A-I/PT

DSPIC33FJ128MC510A-I/PTC31

DSPIC33FJ128MC510AT-E/PT

DSPIC33FJ128MC510AT-I/PT

DSPIC33FJ128MC510AT-I/PTC27

DSPIC33FJ128MC510AT-I/PTC30

DSPIC33FJ128MC510-I/PT

DSPIC33FJ128MC510-I/PTC21

DSPIC33FJ128MC510-I/PTC22

DSPIC33FJ128MC510T-I/PTC21

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DSPIC33FJ128MC510T-I/PTC22

DSPIC33FJ128MC710A-E/PT

DSPIC33FJ128MC710A-H/PT

DSPIC33FJ128MC710A-I/PT

DSPIC33FJ128MC710AT-E/PT

DSPIC33FJ128MC710AT-H/PT

DSPIC33FJ128MC710AT-I/PT

DSPIC33FJ128MC710-I/PT

DSPIC33FJ256GP510A-I/PT

DSPIC33FJ256GP510-I/PT

DSPIC33FJ256GP710A-E/PT

DSPIC33FJ256GP710A-H/PT

DSPIC33FJ256GP710A-I/PT

DSPIC33FJ256GP710AT-E/PT

DSPIC33FJ256GP710AT-I/PT

DSPIC33FJ256GP710-I/PT

DSPIC33FJ256GP710-I/PTB21

DSPIC33FJ256GP710T-I/PT

DSPIC33FJ256GP710T-I/PTB21

DSPIC33FJ256MC510A-E/PT

DSPIC33FJ256MC510A-I/PT

DSPIC33FJ256MC510AT-I/PT

DSPIC33FJ256MC510-I/PT

DSPIC33FJ256MC510T-I/PT

DSPIC33FJ256MC710A-E/PT

DSPIC33FJ256MC710A-H/PT

DSPIC33FJ256MC710A-I/PT

DSPIC33FJ256MC710AT-E/PT

DSPIC33FJ256MC710AT-I/PT

DSPIC33FJ256MC710-I/PT

DSPIC33FJ256MC710T-I/PT

DSPIC33FJ32GS610-50I/PT

DSPIC33FJ32GS610-E/PT

DSPIC33FJ32GS610-I/PT

DSPIC33FJ32GS610T-50I/PT

DSPIC33FJ64GP310A-E/PT

DSPIC33FJ64GP310A-I/PT

DSPIC33FJ64GP310AT-E/PT

DSPIC33FJ64GP310AT-I/PT

DSPIC33FJ64GP310-I/PT

DSPIC33FJ64GP710A-E/PT

DSPIC33FJ64GP710A-I/PT

DSPIC33FJ64GP710AT-E/PT

DSPIC33FJ64GP710AT-I/PT

DSPIC33FJ64GP710-I/PT

DSPIC33FJ64GS610-50I/PT

DSPIC33FJ64GS610-E/PT

DSPIC33FJ64GS610-I/PT

DSPIC33FJ64GS610T-50I/PT

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DSPIC33FJ64MC510A-E/PT

DSPIC33FJ64MC510A-I/PT

DSPIC33FJ64MC510AT-E/PT

DSPIC33FJ64MC510AT-I/PT

DSPIC33FJ64MC510-I/PT

DSPIC33FJ64MC710A-E/PT

DSPIC33FJ64MC710A-I/PT

DSPIC33FJ64MC710AT-E/PT

DSPIC33FJ64MC710AT-I/PT

DSPIC33FJ64MC710-I/PT

IC164035-2X

MTR1202-I/PT

PIC18F96J60-I/PT

PIC18F96J65-I/PT

PIC18F97J60-I/PT

PIC18F97J60T-I/PT

PIC24EP256GU810-E/PT

PIC24EP256GU810-I/PT

PIC24EP256GU810T-E/PT

PIC24EP256GU810T-I/PT

PIC24EP512GU810-E/PT

PIC24EP512GU810-I/PT

PIC24EP512GU810T-E/PT

PIC24EP512GU810T-I/PT

PIC24FJ128DA110-I/PT

PIC24FJ128DA210-I/PT

PIC24FJ128GA010-I/PT

PIC24FJ128GA010T-I/PT

PIC24FJ128GA110-E/PT

PIC24FJ128GA110-I/PT

PIC24FJ128GB110-I/PT

PIC32MX775F256LT-80V/PT

PIC32MX775F512L-80I/PT

PIC32MX775F512L-80V/PT

PIC32MX775F512LT-80I/PT

PIC32MX775F512LT-80V/PT

PIC32MX795F512L-80I/PT

PIC32MX795F512L-80I/PTE22

PIC32MX795F512L-80V/PT

PIC32MX795F512LT-80I/PT

PIC32MX795F512LT-80I/PTE21

PIC32MX795F512LT-80I/PTE22

PIC32MX795F512LT-80V/PT